



## Product Change Notification: ALAN-15XDFJ812

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**Date:**

06-Jun-2025

**Product Category:**

Inductive Position Sensors

**Notification Subject:**

CCB 7159 Final Notice: Qualification of 8008MD as a new die attach material for selected LX34070, LX3302A, LX34050 and LX34311 device families available in 14L TSSOP (4.4mm) package.

**Affected CPNs:**

[ALAN-15XDFJ812\\_Affected\\_CPN\\_06062025.pdf](#)

[ALAN-15XDFJ812\\_Affected\\_CPN\\_06062025.csv](#)

**PCN Status:** Final Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of 8008MD as a new die attach material for selected LX34070, LX3302A, LX34050 and LX34311 device families available in 14L TSSOP (4.4mm) package.

**Pre and Post Summary Changes:**

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)
Wire Material	Au	Au
Die Attach Material	2200D	8008MD
Molding Compound Material	G600V	G600V

Lead-Frame Material	C7025	C7025
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**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improved manufacturability by qualifying 8008MD as a new die attach material.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** 15 July 2025 (date code: 2529)

**Note Below EFSD:** Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Timetable Summary:**

	September 2024					>	June 2025				July 2025				
Work Week	36	37	38	39	40		23	24	25	26	27	28	29	30	31
Initial PCN Issue Date			X												
Qual Report Availability							X								
Final PCN Issue Date							X								
Estimated Implementation Date													X		

**Method to Identify Change:** Traceability Code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:** September 18, 2024: Issued initial notification.  
September 19, 2024: Re-issued initial PCN to correct the die attach pre-change material from 3280 to 2200D.  
November 08, 2024: Re-issued initial PCN to update affected parts list to add CPN LX3302AQPW-TR-C01 and remove LX34211QPW-TR, LX34211QPW-TR-VAO, LX3301AQPW and LX3301AQPW-

TR catalog part numbers. Revised "Notification Subject", "Description of Change" and "Qualification Plan" title to reflect the removed parts numbers. Updated Pre and Post Change Summary table to include Lead-frame paddle size and DAP Surface Prep. Added Pre and post change comparison for the Lead-frame drawing.

February 19, 2025: Re-issued initial PCN. Updated Pre and Post Change Summary table by removing the Lead-frame paddle size and DAP Surface Prep, as there are no changes to these. Removed Pre and post change comparison for the Lead-frame drawing. Updated the affected parts list.

June 06, 2025: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on July 15, 2025.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

### **Attachments:**

**[PCN\\_ALAN-15XDFJ812\\_Qual\\_Report.pdf](#)**

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

### **Terms and Conditions:**

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